

WHAT IS CLAIMED IS:

1. A uniform thermal conductive heat dissipation device, comprising a thermal conductor and a plurality of heat pipes, wherein the thermal conductor includes a convex body member and a plurality of connection portions recessed
5 from a convex surface of the body member, and each of the heat pipes includes a heat absorbing portion and a heat dissipation portion, the heat absorbing portion is embedded in the corresponding connection portion
2. The device of Claim 1, wherein the thermal conductor is fabricated from copper.
- 10 3. The device of Claim 1, wherein the thermal conductor includes a semi-cylindrical body member.
4. The device of Claim 1, wherein the body member has a trapezium cross section.
5. The device of Claim 1, wherein the connection portions include a
15 plurality of slots.
6. The device of Claim 1, wherein the connection portions include a plurality of circular channel.
7. The device of Claim 1, wherein the heat pipes include elongate tubes.
- 20 8. The device of Claim 1, wherein the heat pipes include U-shape tubes.
9. The device of Claim 1, further comprising a heat sink mounted to the heat pipes.
10. The device of Claim 9, wherein the bottom of the heat sink is
25 recessed to form a receiving window, and a plurality of connection structures are formed on the surface of the receiving window for receiving the heat dissipation portions of the heat pipes.

11. The device of Claim 10, wherein the connection structures comprise semi-circular slots.

12. The device of Claim 9, wherein the connection structures are conformal to the heat dissipation portions of the heat pipes.

5 13. The device of Claim 12, wherein the connection portions include circular channels.